



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et al.

Serial No.: 10/624,833

Filed: July 22, 2003

**For: METHOD FOR FABRICATING A
CHIP SCALE PACKAGE USING WAFER
LEVEL PROCESSING (as amended)**

Confirmation No.: 6568

Examiner: M. Estrada

Group Art Unit: 2823

**Attorney Docket No.: 2269-3572.2US
(97-1243.02/US)**

Notice of Allowance Mailed:

November 19, 2004

Express Mail Mailing Label No.: EL 994826070 US

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Person making Deposit: Steve Wong

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

**Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450**

Sir:

Please amend the above-referenced application as follows:

*Please
enter
O.C.
3/15/2005*